Refine Search

Search Results -

Terms	Documents
L7	0

Database:

```
US Pre-Grant Publication Full-Text Database
US Patents Full-Text Database
US OCR Full-Text Database
EPO Abstracts Database
JPO Abstracts Database
Derwent World Patents Index
IBM Technical Disclosure Bulletins
```

Search:

```
L8
```

[Refine Search]

[Recall Text] [Clear] [Interrupt]

Search History

DATE: Monday, June 06, 2005   Printable Copy   Create Case

Set Name side by side	Query	Hit Count	Set Name result set
	DB=TDBD; PLUR=YES; OP=OR		
L8	L7	0	L8
	DB=DWPI; PLUR=YES; OP=OR		
L7	L6	0	L7
	DB=JPAB; PLUR=YES; OP=OR		
L6	L5	0	L6
	DB=EPAB; PLUR=YES; OP=OR		
L5	L4	0	L5
	DB=USOC; PLUR=YES; OP=OR		
L4	L3	0	L4
	DB=PGPB; PLUR=YES; OP=OR		
L3	L2	0	L3
	DB=USPT; PLUR=YES; OP=OR		
L2	L1 and (wafer same via same ("bonding pad" or "bonding pads"))	12	L2

L1   ("microchip" or "microdie" or "micro device" or "micro chip" or " micro die") same wafer   820   L1

END OF SEARCH HISTORY

Refine Search

Search Results -

Terms	Documents
passivation and 6777263	0

Database:
US Pre-Grant Publication Full-Text Database
US Patents Full-Text Database
US OCR Full-Text Database
EPO Abstracts Database
JPO Abstracts Database
Derwent World Patents Index
IBM Technical Disclosure Bulletins

Search: L13

Refine Search

Recall Text   Clear   Interrupt

Search History

DATE: Monday, June 06, 2005   Printable Copy   Create Case

Set Name Query	Hit Count	Set Name
side by side		result set
DB=USPT; PLUR=YES; OP=OR		
L13 passivation and 6777263	0	L13
L12 5801068 and passivation	0	L12
L11 L6 and passivation	0	L11
L10 ("anodic bonding" near10 seal$5) same packag$5	11	L10
L9 "anoding bonding" near10 sealant	0	L9
L8 ("glas frit" near10 seal$5) same packag$5	0	L8
L7 "glas frit" near10 sealant	0	L7
L6 5144412 and seal$6	5	L6
L5 L4 and "bonding pad"	12	L5
L4 L3 and via	116	L4
L3 L1 same packag$5 same "cup"	286	L3
L2 L1 packag$5 same "cup"	448194	L2
L1 chip or die	444766	L1

END OF SEARCH HISTORY

Refine Search

Search Results -

Terms	Documents
L4 and "bonding pad"	12

Database:
US Pre-Grant Publication Full-Text Database
US Patents Full-Text Database
US OCR Full-Text Database
EPO Abstracts Database
JPO Abstracts Database
Derwent World Patents Index
IBM Technical Disclosure Bulletins

Search:
L5

Refine Search

Recall Text   Clear   Interrupt

Search History

DATE: Monday, June 06, 2005   Printable Copy   Create Case

Set Name Query	Hit Count	Set Name
side by side		result set

DB=USPT; PLUR=YES; OP=OR

Set Name	Query	Hit Count	Set Name
L5	L4 and "bonding pad"	12	L5
L4	L3 and via	116	L4
L3	L1 same packag$5 same "cup"	286	L3
L2	L1 packag$5 same "cup"	448194	L2
L1	chip or die	444766	L1

END OF SEARCH HISTORY